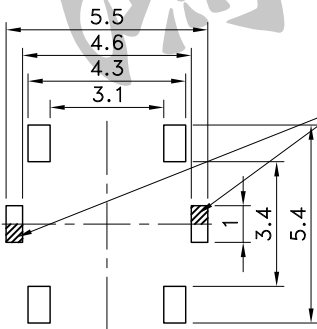
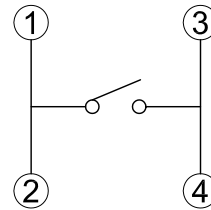


P.C.B TERMINAL POSITION

CIRCUIT ARRANGEMENT

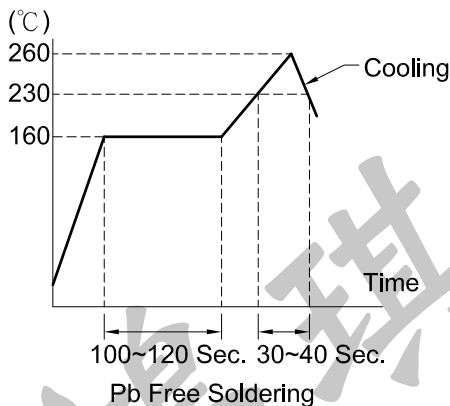


GROUND PIN:
 The thickness of cream solder: 150~200 μ
 We recommend to connect the GND land shown in the switch spec. with the GND of your P.C.B for withstanding electric-static discharge.





REFLOW SOLDERING CONDITIONS

SPECIFICATIONS



- | | |
|--------------------------|---|
| 1. Rating | : DC 15V 20mA |
| 2. Contact Resistance | : 50m Ω Max. |
| 3. Insulation Resistance | : 50M Ω Min. at DC 100V |
| 4. Dielectric Strength | : AC 250V for 1 Minute |
| 5. Operating Force | : 350 \pm 100gf |
| 6. Circuit | : SPST |
| 7. Stroke | : 0.25 ^{+0.1} _{-0.2} mm |
| 8. Life | : 200,000 Cycles |
| 9. Taping | : 5,000 Pcs/Reel |

REVISION:		DATE:		REVISION:		DATE:	
UNIT:mm		THIRD ANGLE PROJECTION METHOD		TOL. UNLESS OTHERWISE STATED: ± 0.3		CODE NO.:HCH-2126	
ISSUED		CONFIRMED		PART NO.		STS-06-C	
 2017.10.02		 2017.10.02		 HORNG CHIH 鴻琪股份有限公司 <small>ISO9001 Certified ISO14001 Certified</small>			